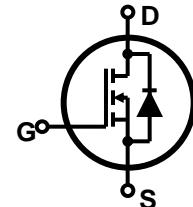
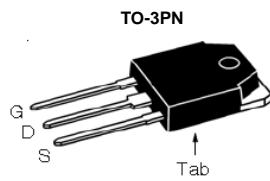


Features

- Low gate charge
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant
- JEDEC Qualification

N-channel MOSFET		
BV_{DSS}	I_D	$R_{DS(on)}$
900V	9.5A	< 1.4Ω



Device	Package	Marking	Remark
TMAN9N90	TO-3PN	TMAN9N90	RoHS

Absolute Maximum Ratings

Parameter	Symbol	TMAN9N90	Unit
Drain-Source Voltage	V_{DS}	900	V
Gate-Source Voltage	V_{GS}	30	V
Continuous Drain Current $T_C = 25$	I_D	9.5	A
$T_C = 100$		5.9	A
Pulsed Drain Current (Note 1)	I_{DM}	36	A
Single Pulse Avalanche Energy (Note 2)	E_{AS}	210	mJ
Repetitive Avalanche Current (Note 1)	I_{AR}	9.5	A
Repetitive Avalanche Energy (Note 1)	E_{AR}	31.2	mJ
Power Dissipation $T_C = 25$	P_D	312	W
Derate above 25		2.5	W/
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~150	
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	T_L	300	

* Limited only by maximum junction temperature

Thermal Characteristics

Parameter	Symbol	TMAN9N90	Unit
Maximum Thermal resistance, Junction to Case	$R_{θJC}$	0.4	/W
Typical Thermal resistance, Case to Sink(Typical)	$R_{θCS}$	0.24	/W
Maximum Thermal resistance, Junction to Ambient	$R_{θJA}$	40	/W

Electrical Characteristics : $T_c=25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test condition	Min	Typ	Max	Units
OFF						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	900	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 900 \text{ V}, V_{GS} = 0 \text{ V}$	--	--	10	μA
		$V_{DS} = 720 \text{ V}, T_C = 125 \text{ C}$	--	--	100	μA
Forward Gate-Source Leakage Current	I_{GSSF}	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$	--	--	100	nA
Reverse Gate-Source Leakage Current	I_{GSSR}	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$	--	--	-100	nA

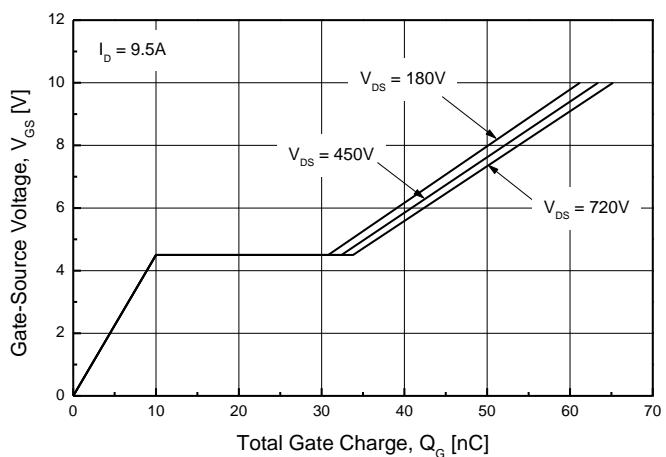
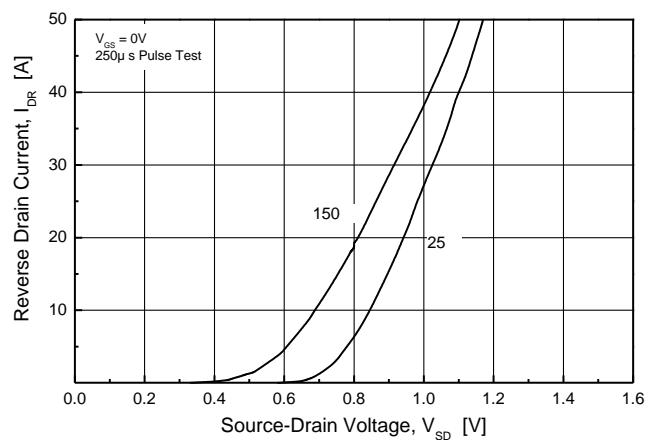
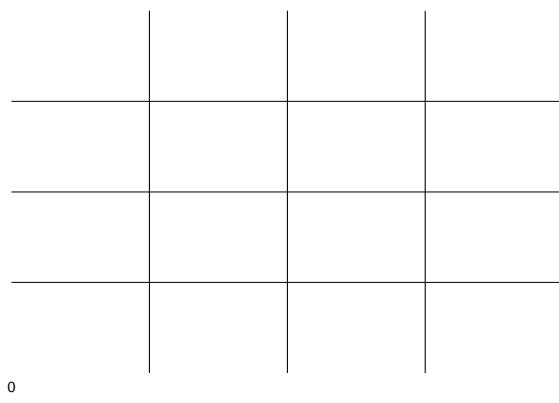
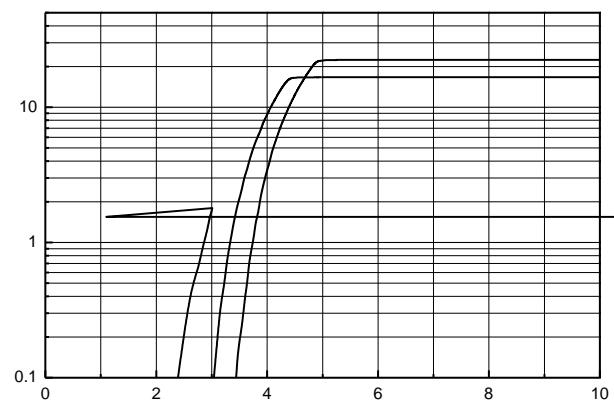
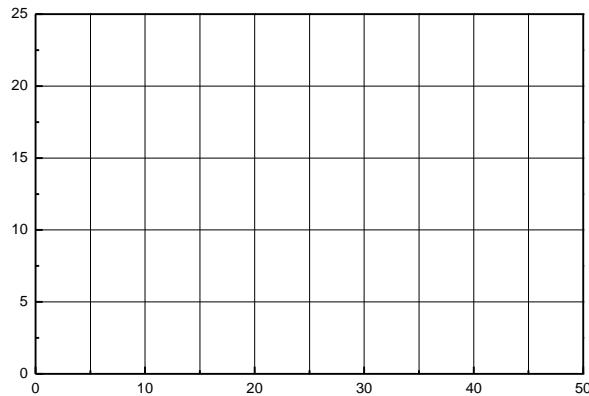
ON

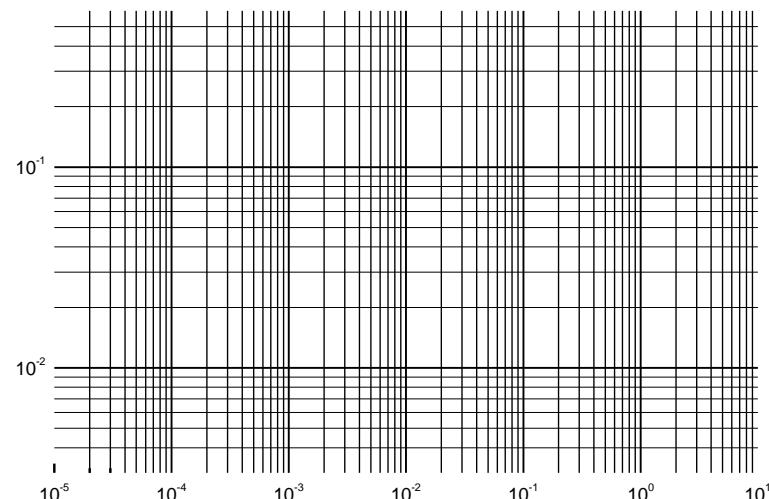
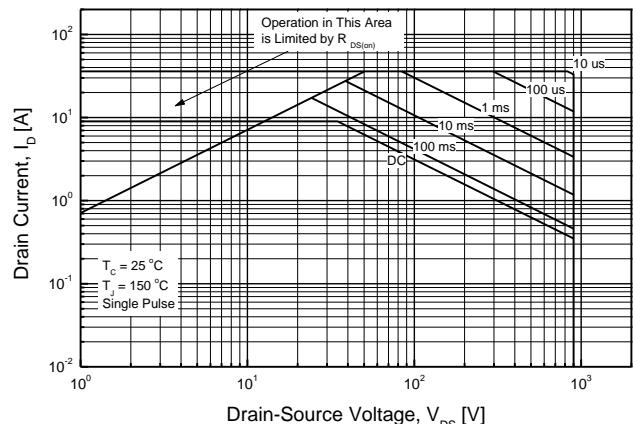
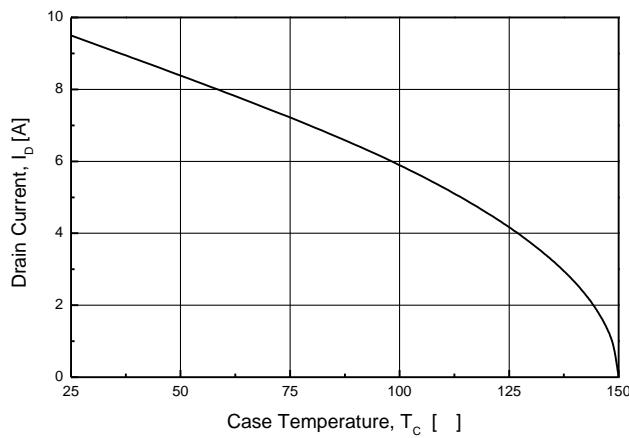
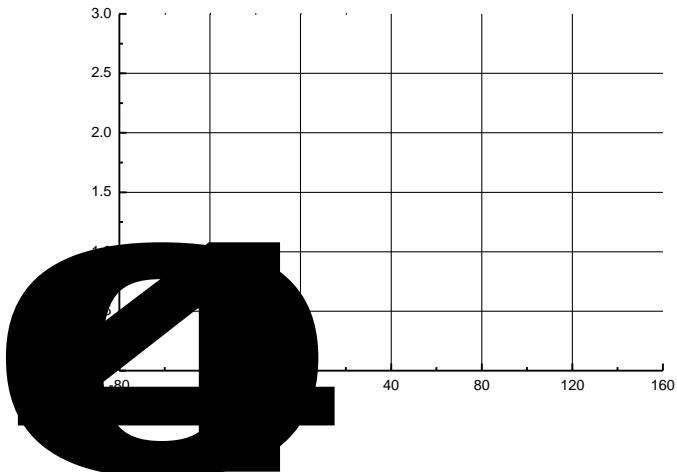
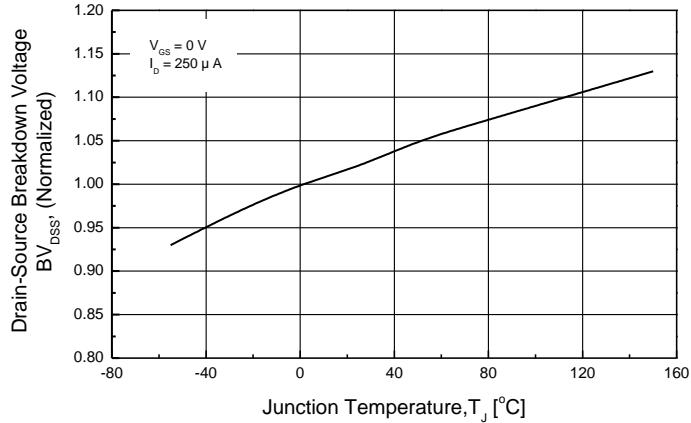
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	2	--	4	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = 10 V$, $I_D = 4.75 A$	-- --			

Note :

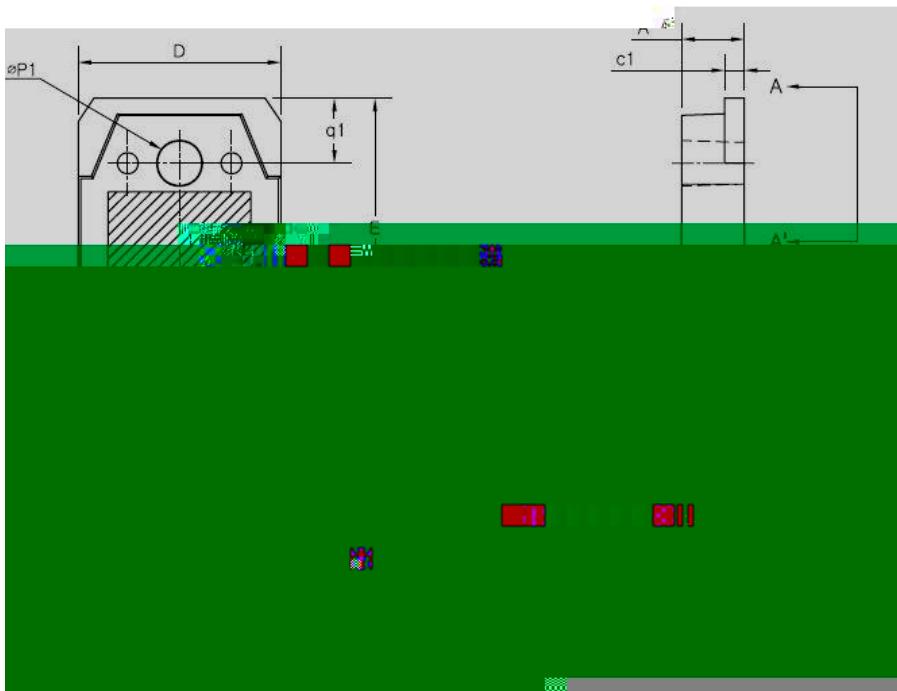
- NOTE :

 1. Repeated rating : Pulse width limited by safe operating area
 2. $L = 4.4mH$, $I_{AS} = 9.5A$, $V_{DD} = 50V$, $R_G = 25\Omega$, Starting $T_J = 25^\circ C$, not subject to production test – verified by design/characterization
 3. $I_{SD} = 9.5A$, $dI/dt = 200A/\mu s$, $V_{DD} = BV_{DS}$, Starting $T_J = 25^\circ C$
 4. Pulse Test :Pulse width 300 μs , Duty Cycle 2%
 5. Essentially Independent of Operating Temperature Typical Characteristics





TO-3PN MECHANICAL DATA



SYMBOL	MIN	NOM	MAX
A	4.60	4.80	5.00
b	0.80	1.00	1.20
b1	1.80	2.00	2.20
b2	2.80	3.00	3.20
c	0.55	0.60	0.75
c1	1.45	1.50	1.65
D	15.40	15.60	15.80
E	19.70	19.90	20.10
e	5.15	5.45	5.75
L1	3.30	3.50	3.70
L2	19.80	20.00	20.20
øP1	3.30	3.40	3.50
øP2	(3.20)		
Q	2.40	2.60	
q1	4.80	5.00	5.20

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